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Details

Product Status	Obsolete
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, I ² C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	91
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s12dg128mpv

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\$0100 - \$010F**Flash Control Register (fts128k2)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0100	FCLKDIV	Read:	FDIVLD	PRDIV8	FDIV5	FDIV4	FDIV3	FDIV2	FDIV1	FDIV0
		Write:								
\$0101	FSEC	Read:	KEYEN1	KEYEN0	NV5	NV4	NV3	NV2	SEC1	SEC0
		Write:								
\$0102	FTSTMOD	Read:	0	0	0	WRALL	0	0	0	0
		Write:								
\$0103	FCNFG	Read:	CBEIE	CCIE	KEYACC	0	0	0	BKSEL1	BKSEL0
		Write:								
\$0104	FPROT	Read:	FPOPEN	NV6	FPHDIS	FPHS1	FPHS0	FPLDIS	FPLS1	FPLS0
		Write:								
\$0105	FSTAT	Read:	CBEIF	CCIF	PVIOL	ACCERR	0	BLANK	0	0
		Write:								
\$0106	FCMD	Read:	0	CMDB6	CMDB5	0	0	CMDB2	0	CMDB0
		Write:								
\$0107	Reserved for Factory Test	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0108	FADDRHI	Read:	0	Bit 14	13	12	11	10	9	Bit 8
		Write:								
\$0109	FADDRLO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$010A	FDATAHI	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
\$010B	FDATALO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$010C - \$010F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0110 - \$011B**EEPROM Control Register (eets2k)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0110	ECLKDIV	Read:	EDIVLD	PRDIV8	EDIV5	EDIV4	EDIV3	EDIV2	EDIV1	EDIV0
		Write:								
\$0111	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0112	Reserved for Factory Test	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0113	ECNFG	Read:	CBEIE	CCIE	0	0	0	0	0	0
		Write:								
\$0114	EPROT	Read:	EPOPEN	NV6	NV5	NV4	EPDIS	EP2	EP1	EP0
		Write:								
\$0115	ESTAT	Read:	CBEIF	CCIF	PVIOL	ACCERR	0	BLANK	0	0
		Write:								
\$0116	ECMD	Read:	0	CMDB6	CMDB5	0	0	CMDB2	0	CMDB0
		Write:								
\$0117	Reserved for Factory Test	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0118	EADDRHI	Read:	0	0	0	0	0	0	Bit 9	Bit 8
		Write:								

\$0110 - \$011B**EEPROM Control Register (eets2k)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0119	EADDRLO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$011A	EDATAHI	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
\$011B	EDATALO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								

\$011C - \$011F**Reserved for RAM Control Register**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$011C - \$011F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0120 - \$013F**ATD1 (Analog to Digital Converter 10 Bit 8 Channel)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0120	ATD1CTL0	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0121	ATD1CTL1	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0122	ATD1CTL2	Read:	ADPU	AFFC	AWAI	ETRIGLE	ETRIGP	ETRIG	ASCIE	ASCIF
		Write:								
\$0123	ATD1CTL3	Read:	0	S8C	S4C	S2C	S1C	FIFO	FRZ1	FRZ0
		Write:								
\$0124	ATD1CTL4	Read:	SRES8	SMP1	SMP0	PRS4	PRS3	PRS2	PRS1	PRS0
		Write:								
\$0125	ATD1CTL5	Read:	DJM	DSGN	SCAN	MULT	0	CC	CB	CA
		Write:								
\$0126	ATD1STAT0	Read:	SCF	0	ETORF	FIFOR	0	CC2	CC1	CC0
		Write:								
\$0127	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0128	ATD1TEST0	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0129	ATD1TEST1	Read:	0	0	0	0	0	0	0	SC
		Write:								
\$012A	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$012B	ATD1STAT1	Read:	CCF7	CCF6	CCF5	CCF4	CCF3	CCF2	CCF1	CCF0
		Write:								
\$012C	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$012D	ATD1DIEN	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
\$012E	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$012F	PORTAD1	Read:	Bit7	6	5	4	3	2	1	BIT 0
		Write:								

\$0180 - \$01BF**CAN1 (Motorola Scalable CAN - MSCAN)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0185	CAN1RIER	Read:	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
		Write:								
\$0186	CAN1TFLG	Read:	0	0	0	0	0	TXE2	TXE1	TXE0
		Write:								
\$0187	CAN1TIER	Read:	0	0	0	0	0	TXEIE2	TXEIE1	TXEIE0
		Write:								
\$0188	CAN1TARQ	Read:	0	0	0	0	0	ABTRQ2	ABTRQ1	ABTRQ0
		Write:								
\$0189	CAN1TAAK	Read:	0	0	0	0	0	ABTAK2	ABTAK1	ABTAK0
		Write:								
\$018A	CAN1TBSEL	Read:	0	0	0	0	0	TX2	TX1	TX0
		Write:								
\$018B	CAN1IDAC	Read:	0	0	IDAM1	IDAM0	0	IDHIT2	IDHIT1	IDHIT0
		Write:								
\$018C	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$018D	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$018E	CAN1RXERR	Read:	RXERR7	RXERR6	RXERR5	RXERR4	RXERR3	RXERR2	RXERR1	RXERR0
		Write:								
\$018F	CAN1TXERR	Read:	TXERR7	TXERR6	TXERR5	TXERR4	TXERR3	TXERR2	TXERR1	TXERR0
		Write:								
\$0190 - \$0193	CAN1IDAR0 - CAN1IDAR3	Read:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
		Write:								
\$0194 - \$0197	CAN1IDMR0 - CAN1IDMR3	Read:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
		Write:								
\$0198 - \$019B	CAN1IDAR4 - CAN1IDAR7	Read:	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
		Write:								
\$019C - \$019F	CAN1IDMR4 - CAN1IDMR7	Read:	AM7	AM6	AM5	AM4	AM3	AM2	AM1	AM0
		Write:								
\$01A0 - \$01AF	CAN0RXFG	Read:	FOREGROUND RECEIVE BUFFER see (Table 1-2)							
		Write:								
\$01B0 - \$01BF	CAN0TXFG	Read:	FOREGROUND TRANSMIT BUFFER see (Table 1-2)							
		Write:								

\$01C0 - \$01FF**Reserved**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$01C0 - \$01FF	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0200 - \$023F**Reserved**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$020C - \$023F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0240 - \$027F**PIM (Port Integration Module)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0240	PTT	Read:	PTT7	PTT6	PTT5	PTT4	PTT3	PTT2	PTT1	PTT0
		Write:								
\$0241	PTIT	Read:	PTIT7	PTIT6	PTIT5	PTIT4	PTIT3	PTIT2	PTIT1	PTIT0
		Write:								
\$0242	DDRT	Read:	DDRT7	DDRT6	DDRT5	DDRT4	DDRT3	DDRT2	DDRT1	DDRT0
		Write:								
\$0243	RDRT	Read:	RDRT7	RDRT6	RDRT5	RDRT4	RDRT3	RDRT2	RDRT1	RDRT0
		Write:								
\$0244	PERT	Read:	PERT7	PERT6	PERT5	PERT4	PERT3	PERT2	PERT1	PERT0
		Write:								
\$0245	PPST	Read:	PPST7	PPST6	PPST5	PPST4	PPST3	PPST2	PPST1	PPST0
		Write:								
\$0246	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0247	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0248	PTS	Read:	PTS7	PTS6	PTS5	PTS4	PTS3	PTS2	PTS1	PTS0
		Write:								
\$0249	PTIS	Read:	PTIS7	PTIS6	PTIS5	PTIS4	PTIS3	PTIS2	PTIS1	PTIS0
		Write:								
\$024A	DDRS	Read:	DDRS7	DDRS6	DDRS5	DDRS4	DDRS3	DDRS2	DDRS1	DDRS0
		Write:								
\$024B	RDRS	Read:	RDRS7	RDRS6	RDRS5	RDRS4	RDRS3	RDRS2	RDRS1	RDRS0
		Write:								
\$024C	PERS	Read:	PERS7	PERS6	PERS5	PERS4	PERS3	PERS2	PERS1	PERS0
		Write:								
\$024D	PPSS	Read:	PPSS7	PPSS6	PPSS5	PPSS4	PPSS3	PPSS2	PPSS1	PPSS0
		Write:								
\$024E	WOMS	Read:	WOMS7	WOMS6	WOMS5	WOMS4	WOMS3	WOMS2	WOMS1	WOMS0
		Write:								
\$024F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0250	PTM	Read:	PTM7	PTM6	PTM5	PTM4	PTM3	PTM2	PTM1	PTM0
		Write:								
\$0251	PTIM	Read:	PTIM7	PTIM6	PTIM5	PTIM4	PTIM3	PTIM2	PTIM1	PTIM0
		Write:								
\$0252	DDRM	Read:	DDRM7	DDRM6	DDRM5	DDRM4	DDRM3	DDRM2	DDRM1	DDRM0
		Write:								
\$0253	RDRM	Read:	RDRM7	RDRM6	RDRM5	RDRM4	RDRM3	RDRM2	RDRM1	RDRM0
		Write:								
\$0254	PERM	Read:	PERM7	PERM6	PERM5	PERM4	PERM3	PERM2	PERM1	PERM0
		Write:								
\$0255	PPSM	Read:	PPSM7	PPSM6	PPSM5	PPSM4	PPSM3	PPSM2	PPSM1	PPSM0
		Write:								
\$0256	WOMM	Read:	WOMM7	WOMM6	WOMM5	WOMM4	WOMM3	WOMM2	WOMM1	WOMM0
		Write:								
\$0257	MODRR	Read:	0	0	MODRR5	MODRR4	MODRR3	MODRR2	MODRR1	MODRR0
		Write:								
\$0258	PTP	Read:	PTP7	PTP6	PTP5	PTP4	PTP3	PTP2	PTP1	PTP0
		Write:								

Pin Name Function 1	Pin Name Function 2	Pin Name Function 3	Pin Name Function 4	Pin Name Function 5	Powered by	Internal Pull Resistor		Description
						CTRL	Reset State	
PH6	KWH6	---	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt
PH5	KWH5	---	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt
PH4	KWH4	---	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt
PH3	KWH3	$\overline{SS1}$	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, SS of SPI1
PH2	KWH2	SCK1	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, SCK of SPI1
PH1	KWH1	MOSI1	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, MOSI of SPI1
PH0	KWH0	MISO1	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, MISO of SPI1
PJ7	KWJ7	TXCAN4	SCL	TXCAN0	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, TX of CAN4, SCL of IIC
PJ6	KWJ6	RXCAN4	SDA	RXCAN0	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, RX of CAN4, SDA of IIC
PJ[1:0]	KWJ[1:0]	—	—	—	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupts
PK7	$\overline{ECS}$	ROMCTL	—	—	VDDX	PUCR/ PUPKE	Up	Port K I/O, Emulation Chip Select, ROM Control
PK[5:0]	XADDR[19: 14]	—	—	—	VDDX	PUCR/ PUPKE	Up	Port K I/O, Extended Addresses
PM7	BF_PSLM	TXCAN4	—	—	VDDX	PERM/ PPSM	Disabled	Port M I/O, BF slot mismatch pulse, TX of CAN4
PM6	BF_PERR	RXCAN4	—	—	VDDX	PERM/ PPSM	Disabled	Port M I/O, BF illegal pulse/message format error pulse, RX of CAN4
PM5	BF_PROK	TXCAN0	TXCAN4	SCK0	VDDX	PERM/ PPSM	Disabled	Port M I/O, BF reception ok pulse, TX of CAN0, CAN4, SCK of SPI0
PM4	BF_PSYN	RXCAN0	RXCAN4	MOSI0	VDDX	PERM/ PPSM	Disabled	Port M I/O, BF sync pulse (Rx/Tx) OK pulse o/p, RX of CAN0, CAN4, MOSI of SPI0
PM3	TX_BF	TXCAN1	TXCAN0	$\overline{SS0}$	VDDX	PERM/ PPSM	Disabled	Port M I/O, TX of BF, CAN1, CAN0, $\overline{SS}$ of SPI0
PM2	RX_BF	RXCAN1	RXCAN0	MISO0	VDDX	PERM/ PPSM	Disabled	Port M I/O, RX of BF, CAN1, CAN0, MISO of SPI0

2.3.13 PE6 / MODB / IPIPE1 — Port E I/O Pin 6

PE6 is a general purpose input or output pin. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODB bit at the rising edge of $\overline{\text{RESET}}$. This pin is shared with the instruction queue tracking signal IPIPE1. This pin is an input with a pull-down device which is only active when $\overline{\text{RESET}}$ is low.

2.3.14 PE5 / MODA / IPIPE0 — Port E I/O Pin 5

PE5 is a general purpose input or output pin. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODA bit at the rising edge of $\overline{\text{RESET}}$. This pin is shared with the instruction queue tracking signal IPIPE0. This pin is an input with a pull-down device which is only active when $\overline{\text{RESET}}$ is low.

2.3.15 PE4 / ECLK — Port E I/O Pin 4

PE4 is a general purpose input or output pin. It can be configured to drive the internal bus clock ECLK. ECLK can be used as a timing reference.

2.3.16 PE3 / $\overline{\text{LSTRB}}$ / $\overline{\text{TAGLO}}$ — Port E I/O Pin 3

PE3 is a general purpose input or output pin. In MCU expanded modes of operation, $\overline{\text{LSTRB}}$ can be used for the low-byte strobe function to indicate the type of bus access and when instruction tagging is on, $\overline{\text{TAGLO}}$ is used to tag the low half of the instruction word being read into the instruction queue.

2.3.17 PE2 / $\overline{\text{R/W}}$ — Port E I/O Pin 2

PE2 is a general purpose input or output pin. In MCU expanded modes of operations, this pin drives the read/write output signal for the external bus. It indicates the direction of data on the external bus.

2.3.18 PE1 / $\overline{\text{IRQ}}$ — Port E Input Pin 1

PE1 is a general purpose input pin and the maskable interrupt request input that provides a means of applying asynchronous interrupt requests. This will wake up the MCU from STOP or WAIT mode.

2.3.19 PE0 / $\overline{\text{XIRQ}}$ — Port E Input Pin 0

PE0 is a general purpose input pin and the non-maskable interrupt request input that provides a means of applying asynchronous interrupt requests. This will wake up the MCU from STOP or WAIT mode.

2.3.20 PH7 / KWH7 — Port H I/O Pin 7

PH7 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode.

Section 4 Modes of Operation

4.1 Overview

Eight possible modes determine the operating configuration of the MC9S12DT128. Each mode has an associated default memory map and external bus configuration controlled by a further pin.

Three low power modes exist for the device.

4.2 Chip Configuration Summary

The operating mode out of reset is determined by the states of the MODC, MODB, and MODA pins during reset (**Table 4-1**). The MODC, MODB, and MODA bits in the MODE register show the current operating mode and provide limited mode switching during operation. The states of the MODC, MODB, and MODA pins are latched into these bits on the rising edge of the reset signal. The ROMCTL signal allows the setting of the ROMON bit in the MISC register thus controlling whether the internal Flash is visible in the memory map. ROMON = 1 mean the Flash is visible in the memory map. The state of the ROMCTL pin is latched into the ROMON bit in the MISC register on the rising edge of the reset signal.

Table 4-1 Mode Selection

BKGD = MODC	PE6 = MODB	PE5 = MODA	PK7 = ROMCTL	ROMON Bit	Mode Description
0	0	0	X	1	Special Single Chip, BDM allowed and ACTIVE. BDM is allowed in all other modes but a serial command is required to make BDM active.
0	0	1	0	1	Emulation Expanded Narrow, BDM allowed
			1	0	
0	1	0	X	0	Special Test (Expanded Wide), BDM allowed
0	1	1	0	1	Emulation Expanded Wide, BDM allowed
			1	0	
1	0	0	X	1	Normal Single Chip, BDM allowed
1	0	1	0	0	Normal Expanded Narrow, BDM allowed
			1	1	
1	1	0	X	1	Special Peripheral; BDM allowed but bus operations would cause bus conflicts (must not be used)
1	1	1	0	0	Normal Expanded Wide, BDM allowed
			1	1	

For further explanation on the modes refer to the HCS12 Multiplexed External Bus Interface Block Guide.

Table 4-2 Clock Selection Based on PE7

PE7 = $\overline{\text{XCLKS}}$	Description
1	Colpitts Oscillator selected
0	Pierce Oscillator/external clock selected

6.4 HCS12 Interrupt (INT) Block Description

Consult the INT Block Guide for information on the HCS12 Interrupt module.

6.5 HCS12 Background Debug Module (BDM) Block Description

Consult the BDM Block Guide for information on the HCS12 Background Debug module.

6.5.1 Device-specific information

When the BDM Block Guide refers to *alternate clock* this is equivalent to *oscillator clock*.

6.6 HCS12 Breakpoint (BKP) Block Description

Consult the BKP Block Guide for information on the HCS12 Breakpoint module.

Section 7 Clock and Reset Generator (CRG) Block Description

Consult the CRG Block User Guide for information about the Clock and Reset Generator module.

7.1 Device-specific information

The Low Voltage Reset feature of the CRG is not available on this device.

Section 8 Oscillator (OSC) Block Description

Consult the OSC Block User Guide for information about the Oscillator module.

8.1 Device-specific information

The $\overline{\text{XCLKS}}$ input signal is active low (see 2.3.12 PE / NOACC / $\overline{\text{XCLKS}}$ — Port E I/O Pin 7).

Section 9 Enhanced Capture Timer (ECT) Block Description

Section 23 Printed Circuit Board Layout Proposal

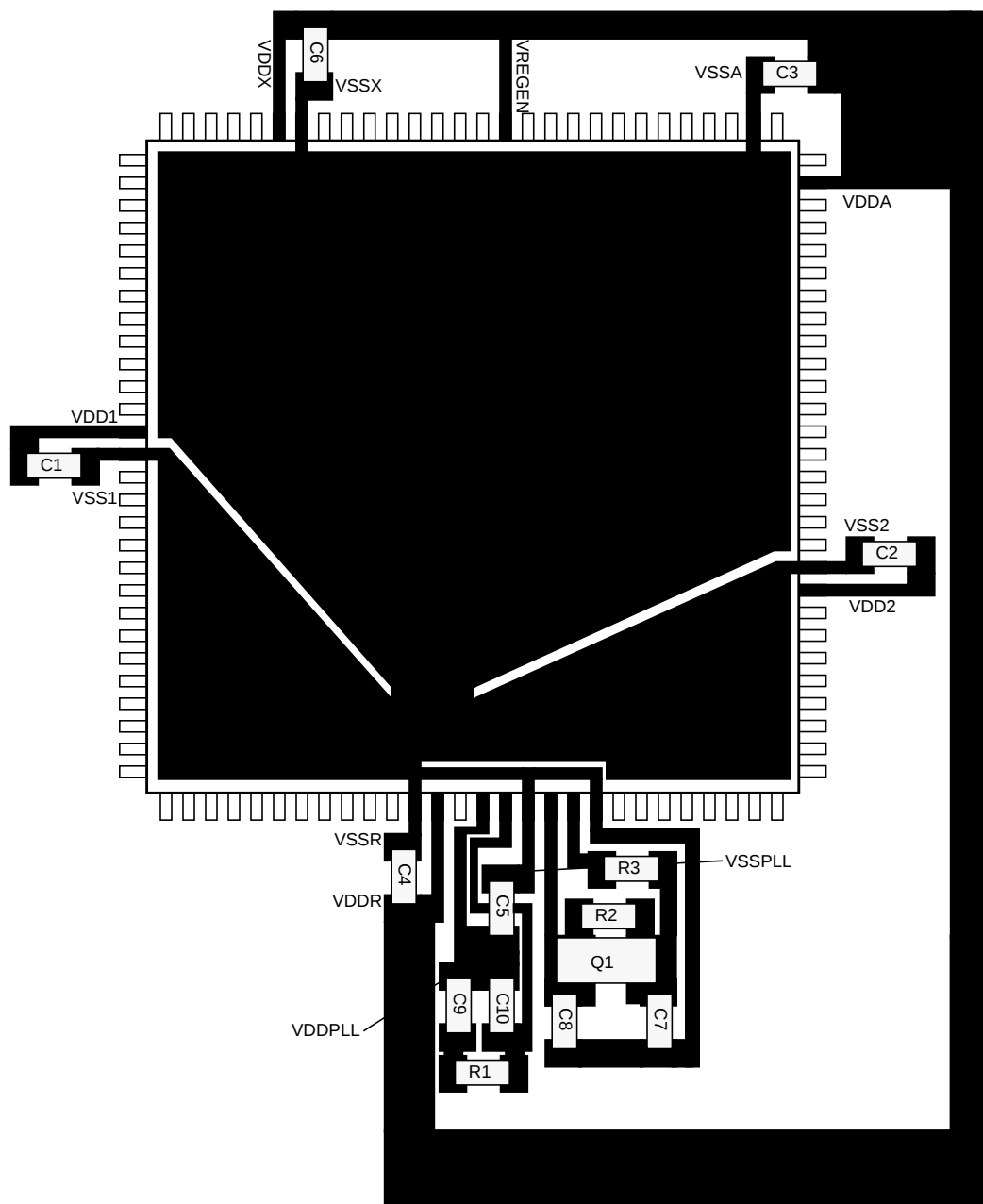
Table 23-1 Suggested External Component Values

Component	Purpose	Type	Value
C1	VDD1 filter cap	ceramic X7R	100 ... 220nF
C2	VDD2 filter cap	ceramic X7R	100 ... 220nF
C3	VDDA filter cap	ceramic X7R	100nF
C4	VDDR filter cap	X7R/tantalum	>= 100nF
C5	VDDPLL filter cap	ceramic X7R	100nF
C6	VDDX filter cap	X7R/tantalum	>= 100nF
C7	OSC load cap		
C8	OSC load cap		
C9 / C _S	PLL loop filter cap	See PLL specification chapter	
C10 / C _P	PLL loop filter cap		
C11 / C _{DC}	DC cutoff cap	Colpitts mode only, if recommended by quartz manufacturer	
R1 / R	PLL loop filter res	See PLL Specification chapter	
R2 / R _B		Pierce mode only	
R3 / R _S			
Q1	Quartz		

The PCB must be carefully laid out to ensure proper operation of the voltage regulator as well as of the MCU itself. The following rules must be observed:

- Every supply pair must be decoupled by a ceramic capacitor connected as near as possible to the corresponding pins (C1 – C6).
- Central point of the ground star should be the VSSR pin.
- Use low ohmic low inductance connections between VSS1, VSS2 and VSSR.
- VSSPLL must be directly connected to VSSR.
- Keep traces of VSSPLL, EXTAL and XTAL as short as possible and occupied board area for C7, C8, C11 and Q1 as small as possible.
- Do not place other signals or supplies underneath area occupied by C7, C8, C10 and Q1 and the connection area to the MCU.
- Central power input should be fed in at the VDDA/VSSA pins.

Figure 23-3 Recommended PCB Layout for 112LQFP Pierce Oscillator



NOTE: In the following context VDD5 is used for either VDDA, VDDR and VDDX; VSS5 is used for either VSSA, VSSR and VSSX unless otherwise noted. IDD5 denotes the sum of the currents flowing into the VDDA, VDDX and VDDR pins. VDD is used for VDD1, VDD2 and VDDPLL, VSS is used for VSS1, VSS2 and VSSPLL. IDD is used for the sum of the currents flowing into VDD1 and VDD2.

A.1.3 Pins

There are four groups of functional pins.

A.1.3.1 5V I/O pins

Those I/O pins have a nominal level of 5V. This class of pins is comprised of all port I/O pins, the analog inputs, BKGD pin and the RESET inputs. The internal structure of all those pins is identical, however some of the functionality may be disabled. E.g. for the analog inputs the output drivers, pull-up and pull-down resistors are disabled permanently.

A.1.3.2 Analog Reference

This class is made up by the two VRH and VRL pins.

A.1.3.3 Oscillator

The pins XFC, EXTAL, XTAL dedicated to the oscillator have a nominal 2.5V level. They are supplied by VDDPLL.

A.1.3.4 TEST

This pin is used for production testing only.

A.1.3.5 VREGEN

This pin is used to enable the on chip voltage regulator.

A.1.4 Current Injection

Power supply must maintain regulation within operating V_{DD5} or V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current ($V_{in} > V_{DD5}$) is greater than I_{DD5} , the injection current may flow out of VDD5 and could result in external power supply going out of regulation. Insure external VDD5 load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power; e.g. if no system clock is present, or if clock rate is very low which would reduce overall power consumption.

A.1.5 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only. A functional operation under or outside those maxima is not guaranteed. Stress beyond those limits may affect the reliability or cause permanent damage of the device.

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either V_{SS5} or V_{DD5}).

Table A-1 Absolute Maximum Ratings¹

Num	Rating	Symbol	Min	Max	Unit
1	I/O, Regulator and Analog Supply Voltage	V_{DD5}	-0.3	6.0	V
2	Digital Logic Supply Voltage ²	V_{DD}	-0.3	3.0	V
3	PLL Supply Voltage ⁽²⁾	V_{DDPLL}	-0.3	3.0	V
4	Voltage difference VDDX to VDDR and VDDA	ΔV_{DDX}	-0.3	0.3	V
5	Voltage difference VSSX to VSSR and VSSA	ΔV_{SSX}	-0.3	0.3	V
6	Digital I/O Input Voltage	V_{IN}	-0.3	6.0	V
7	Analog Reference	V_{RH}, V_{RL}	-0.3	6.0	V
8	XFC, EXTAL, XTAL inputs	V_{ILV}	-0.3	3.0	V
9	TEST input	V_{TEST}	-0.3	10.0	V
10	Instantaneous Maximum Current Single pin limit for all digital I/O pins ³	I_D	-25	+25	mA
11	Instantaneous Maximum Current Single pin limit for XFC, EXTAL, XTAL ⁴	I_{DL}	-25	+25	mA
12	Instantaneous Maximum Current Single pin limit for TEST ⁵	I_{DT}	-0.25	0	mA
13	Storage Temperature Range	T_{stg}	- 65	155	°C

NOTES:

1. Beyond absolute maximum ratings device might be damaged.
2. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The absolute maximum ratings apply when the device is powered from an external source.
3. All digital I/O pins are internally clamped to V_{SSX} and V_{DDX} , V_{SSR} and V_{DDR} or V_{SSA} and V_{DDA} .
4. Those pins are internally clamped to V_{SSPLL} and V_{DDPLL} .
5. This pin is clamped low to V_{SSX} , but not clamped high. This pin must be tied low in applications.

A.1.6 ESD Protection and Latch-up Immunity

All ESD testing is in conformity with CDF-AEC-Q100 Stress test qualification for Automotive Grade Integrated Circuits. During the device qualification ESD stresses were performed for the Human Body Model (HBM), the Machine Model (MM) and the Charge Device Model.

calculations refer to **Section A.1.8 Power Dissipation and Thermal Characteristics**.

Table A-4 Operating Conditions

Rating	Symbol	Min	Typ	Max	Unit
I/O, Regulator and Analog Supply Voltage	V_{DD5}	4.5	5	5.25	V
Digital Logic Supply Voltage ¹	V_{DD}	2.35	2.5	2.75	V
PLL Supply Voltage ¹	V_{DDPLL}	2.25	2.5	2.75	V
Voltage Difference VDDX to VDDR and VDDA	ΔV_{DDX}	-0.1	0	0.1	V
Voltage Difference VSSX to VSSR and VSSA	ΔV_{SSX}	-0.1	0	0.1	V
Bus Frequency	f_{bus}	0.25 ²	-	25	MHz
MC9S12DT128C					
Operating Junction Temperature Range	T_J	-40	-	100	°C
Operating Ambient Temperature Range ³	T_A	-40	27	85	°C
MC9S12DT128V					
Operating Junction Temperature Range	T_J	-40	-	120	°C
Operating Ambient Temperature Range ³	T_A	-40	27	105	°C
MC9S12DT128M					
Operating Junction Temperature Range	T_J	-40	-	140	°C
Operating Ambient Temperature Range ³	T_A	-40	27	125	°C

NOTES:

1. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The given operating range applies when this regulator is disabled and the device is powered from an external source.
2. Some blocks e.g. ATD (conversion) and NVMs (program/erase) require higher bus frequencies for proper operation.
3. Please refer to **Section A.1.8 Power Dissipation and Thermal Characteristics** for more details about the relation between ambient temperature T_A and device junction temperature T_J .

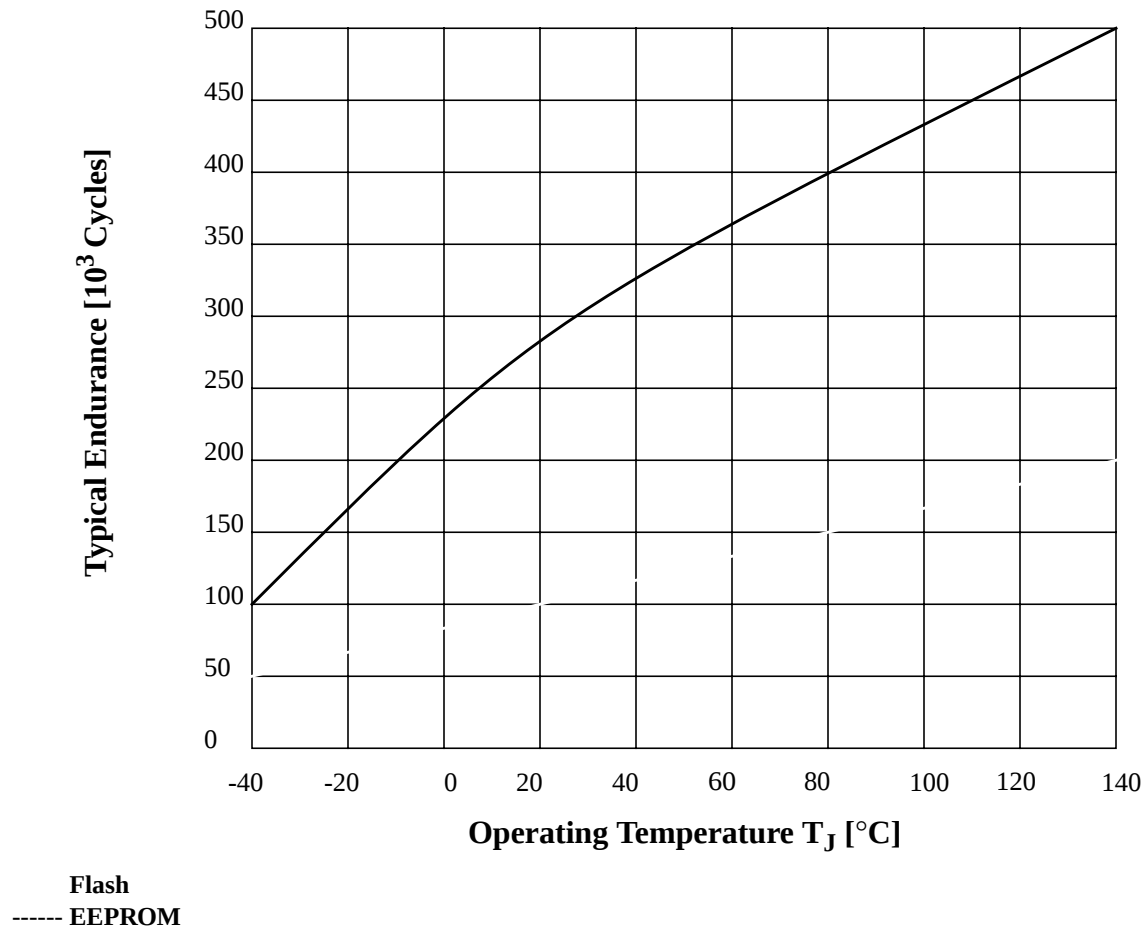
A.1.8 Power Dissipation and Thermal Characteristics

Power dissipation and thermal characteristics are closely related. The user must assure that the maximum operating junction temperature is not exceeded. The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_J = T_A + (P_D \cdot \Theta_{JA})$$

T_J = Junction Temperature, [°C]

T_A = Ambient Temperature, [°C]

Figure A-2 Typical Endurance vs Temperature

B.2 112-pin LQFP package

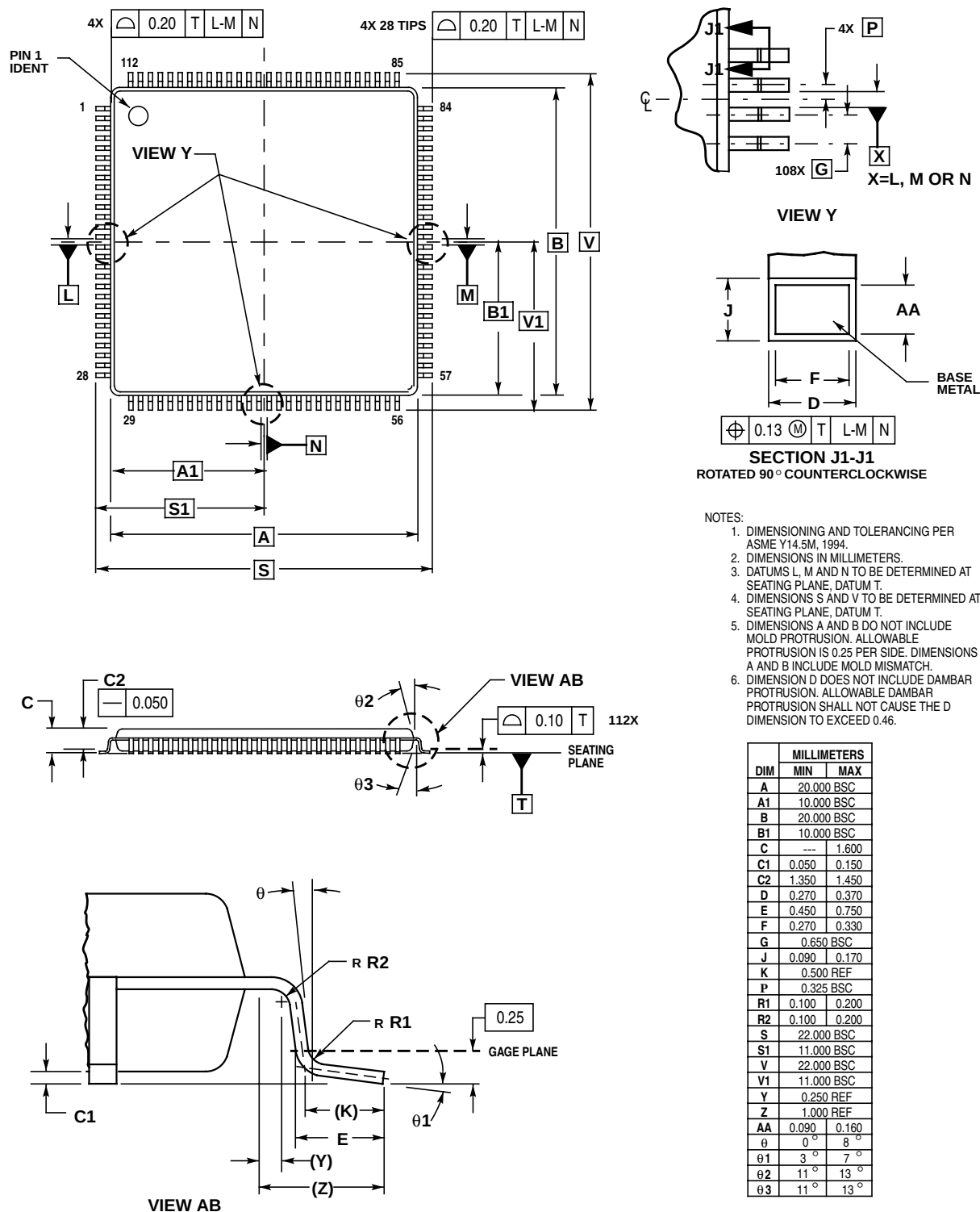


Figure 23-6 112-pin LQFP mechanical dimensions (case no. 987)